

/ Revised record

	! " #	\$! % & '	! () % * +	, -	. /
G		0 &	$V_{GS(th)}$ 的测试条件原先为: $V_{DS}=10V$ $I_D=1mA$ 改成: $V_{DS}=V_{GS}$ $I_D=250\mu A$	1 2 3	4 5 6
			7 8 9 : ; < = > ? @ A < = B C	D E	4 5 6
			VTH 英文描述 Drain-Source Diode Forward Voltage 更正为 Gate Threshold Voltage	D E	

/ Descriptions

SOT-23 F G G H N I J MOS K L M N ON-CHANNEL MOSFET in a SOT-23 Plastic Package.

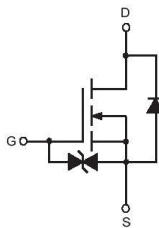
/ Features

P Q % R - S T U V W X Y Z % [\ V W O] V ^ _ ` O < = B C O
Sensitive gate trigger current and Low Holding current.ESD protected up to 1KV. HF product.

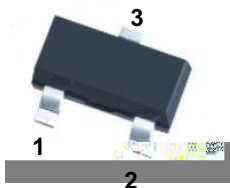
/ Applications

a b c d % e f X g h R - O
Intended for use in general purpose switching and phase control applications.

/ Equivalent Circuit



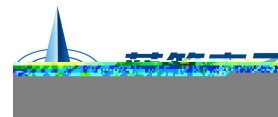
/ Pinning



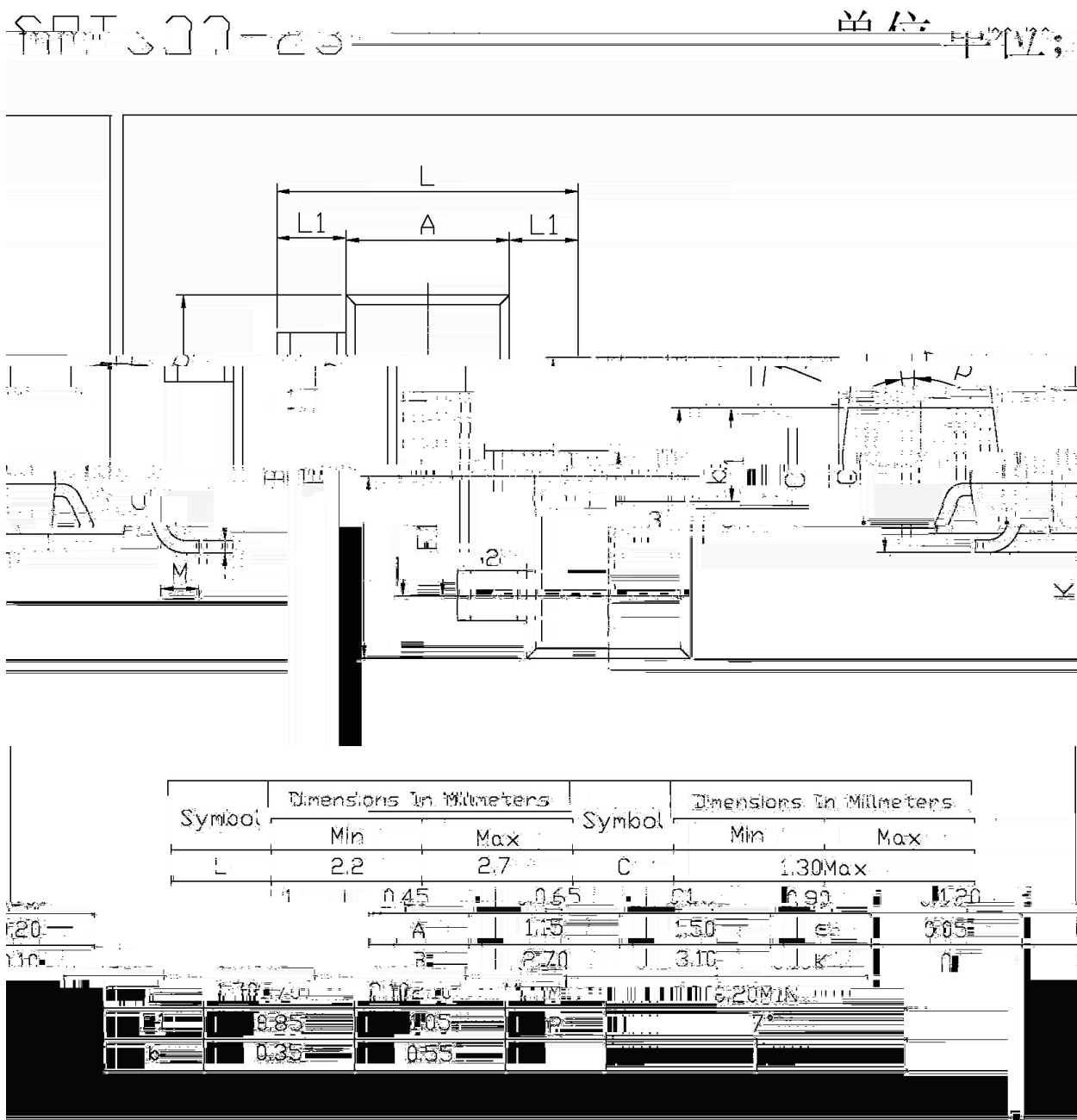
PIN1 i G PIN 2 i S PIN 3 i D

/ Marking

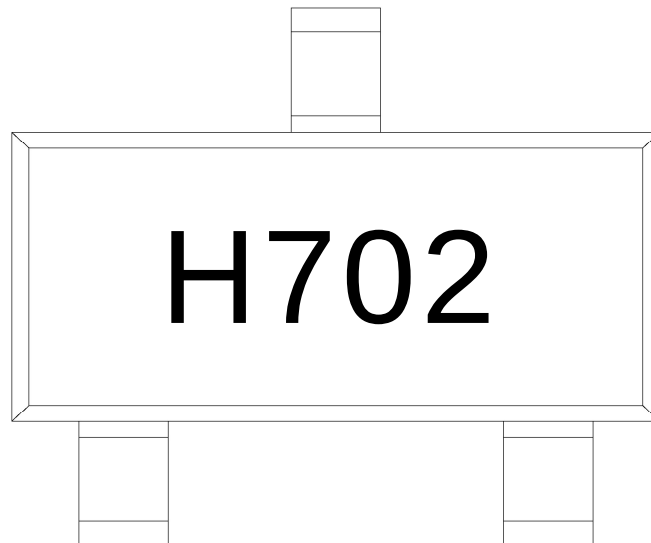
Marking	H702
---------	------



/ Package Dimensions



/ Marking Instructions



y z i

H i { | } ~ '

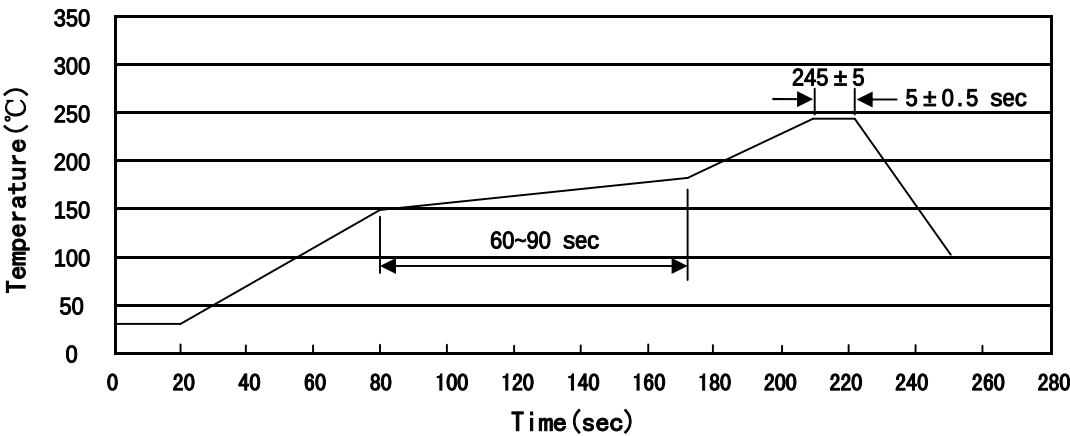
702 i { w m ~ '

Note:

H: Company Code

702: Product Type

() /



说明：

- 1、预热温度 150 ~ 180℃，时间 60 ~ 90sec；
- 2、峰值温度 245±5℃，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10℃/sec.

Note:

- 1.Preheating:150~180℃, Time:60~90sec.
- 2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

/ Notices